

## TO-252 N Channel Enhancement 沟道增强型 MOS Field Effect Transistor 场效应管

### ■Features 特点

Low on-resistance 低导通电阻

$R_{DS(ON)}=3.9m\Omega(\text{Type})@V_{GS}=10V$

$R_{DS(ON)}=6.8m\Omega(\text{Type})@V_{GS}=4.5V$

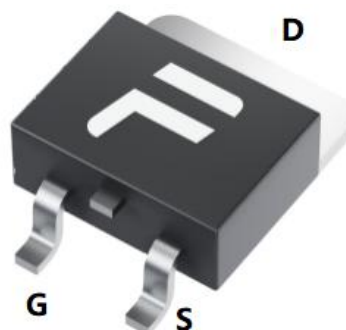
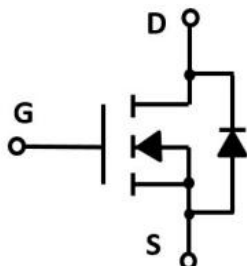
### ■Applications 应用

Load switch 负载开关

DC/DC Converter 升压转换

Power Management 电源管理

### ■Internal Schematic Diagram 内部结构



### ■Absolute Maximum Ratings 最大额定值

| Characteristic 特性参数                         | Symbol 符号                                | Rat 额定值  | Unit 单位                   |
|---------------------------------------------|------------------------------------------|----------|---------------------------|
| Drain-Source Voltage 漏极-源极电压                | $BV_{DSS}$                               | 30       | V                         |
| Gate- Source Voltage 栅极-源极电压                | $V_{GS}$                                 | $\pm 20$ | V                         |
| Drain Current (continuous)漏极电流-连续           | $I_D$ (at $T_C = 25^\circ\text{C}$ )     | 80       | A                         |
| Drain Current (pulsed)漏极电流-脉冲               | $I_{DM}$                                 | 280      | A                         |
| Total Device Dissipation 总耗散功率              | $P_D(\text{at } T_C = 25^\circ\text{C})$ | 50       | W                         |
| Thermal Resistance Junction-Ambient/Case 热阻 | $R_{\theta JA}/R_{\theta JC}$            | 31/2.5   | $^\circ\text{C}/\text{W}$ |
| Avalanche Energy Single Pulse 雪崩能量          | $E_{AS}$                                 | 81       | mJ                        |
| Junction/Storage Temperature 结温/储存温度        | $T_J, T_{stg}$                           | -55~150  | $^\circ\text{C}$          |

**■ Electrical Characteristics 电特性**

 (T<sub>A</sub>=25°C unless otherwise noted 如无特殊说明, 温度为 25°C)

| Characteristic<br>特性参数                                                                                                                         | Symbol<br>符号        | Min<br>最小值 | Typ<br>典型值 | Max<br>最大值 | Unit<br>单位 |
|------------------------------------------------------------------------------------------------------------------------------------------------|---------------------|------------|------------|------------|------------|
| Drain-Source Breakdown Voltage<br>漏极-源极击穿电压(I <sub>D</sub> =250uA, V <sub>GS</sub> =0V)                                                        | BV <sub>DSS</sub>   | 30         | —          | —          | V          |
| Gate Threshold Voltage<br>栅极开启电压(I <sub>D</sub> =250uA, V <sub>GS</sub> =V <sub>DS</sub> )                                                     | V <sub>GS(th)</sub> | 1          | 1.5        | 2          | V          |
| Zero Gate Voltage Drain Current<br>零栅压漏极电流(V <sub>GS</sub> =0V, V <sub>DS</sub> =30V)                                                          | I <sub>DSS</sub>    | —          | —          | 1          | uA         |
| Gate Body Leakage<br>栅极漏电流(V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V)                                                                         | I <sub>GSS</sub>    | —          | —          | ±100       | nA         |
| Static Drain-Source On-State Resistance<br>静态漏源导通电阻(I <sub>D</sub> =30A, V <sub>GS</sub> =10V)<br>(I <sub>D</sub> =25A, V <sub>GS</sub> =4.5V) | R <sub>DS(ON)</sub> | —          | 3.9<br>6.8 | 5.3<br>9.5 | mΩ         |
| Diode Forward Voltage Drop<br>内附二极管正向压降(I <sub>SD</sub> =30A, V <sub>GS</sub> =0V)                                                             | V <sub>SD</sub>     | —          | —          | 1.2        | V          |
| Input Capacitance 输入电容<br>(V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz)                                                                  | C <sub>ISS</sub>    | —          | 1788       | —          | pF         |
| Common Source Output Capacitance<br>共源输出电容(V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz)                                                  | C <sub>OSS</sub>    | —          | 225        | —          | pF         |
| Reverse Transfer Capacitance 反馈电容<br>(V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz)                                                       | C <sub>RSS</sub>    | —          | 180        | —          | pF         |
| Total Gate Charge 栅极电荷密度<br>(V <sub>DS</sub> =15V, I <sub>D</sub> =30A, V <sub>GS</sub> =10V)                                                  | Q <sub>g</sub>      | —          | 34         | —          | nC         |
| Gate Source Charge 栅源电荷密度<br>(V <sub>DS</sub> =15V, I <sub>D</sub> =30A, V <sub>GS</sub> =10V)                                                 | Q <sub>gs</sub>     | —          | 7.5        | —          | nC         |
| Gate Drain Charge 栅漏电荷密度<br>(V <sub>DS</sub> =15V, I <sub>D</sub> =30A, V <sub>GS</sub> =10V)                                                  | Q <sub>gd</sub>     | —          | 6.5        | —          | nC         |
| Turn-ON Delay Time 开启延迟时间<br>(V <sub>DS</sub> =15V I <sub>D</sub> =30A, R <sub>GEN</sub> =3Ω, V <sub>GS</sub> =10V)                            | t <sub>d(on)</sub>  | —          | 7          | —          | ns         |
| Turn-ON Rise Time 开启上升时间<br>(V <sub>DS</sub> =15V I <sub>D</sub> =30A, R <sub>GEN</sub> =3Ω, V <sub>GS</sub> =10V)                             | t <sub>r</sub>      | —          | 4          | —          | ns         |
| Turn-OFF Delay Time 关断延迟时间<br>(V <sub>DS</sub> =15V I <sub>D</sub> =30A, R <sub>GEN</sub> =3Ω, V <sub>GS</sub> =10V)                           | t <sub>d(off)</sub> | —          | 34         | —          | ns         |
| Turn-OFF Fall Time 关断下降时间<br>(V <sub>DS</sub> =15V I <sub>D</sub> =30A, R <sub>GEN</sub> =3Ω, V <sub>GS</sub> =10V)                            | t <sub>f</sub>      | —          | 11         | —          | ns         |

■ Typical Characteristic Curve 典型特性曲线

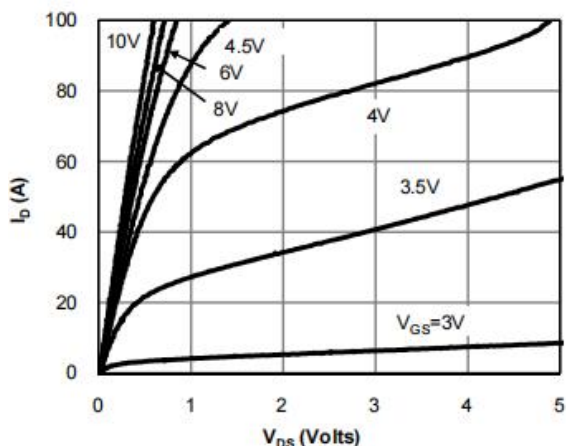


Figure 1: Output Characteristics

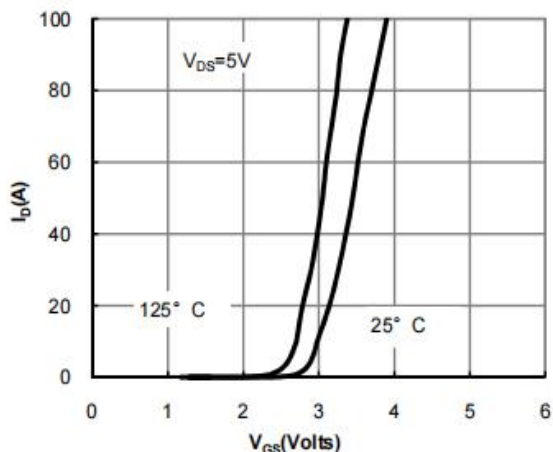


Figure 2: Transfer Characteristics

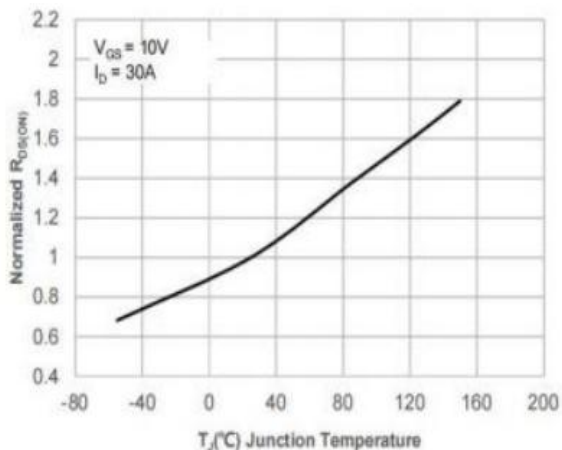


Figure 3: On-Resistance vs.  $T_J$

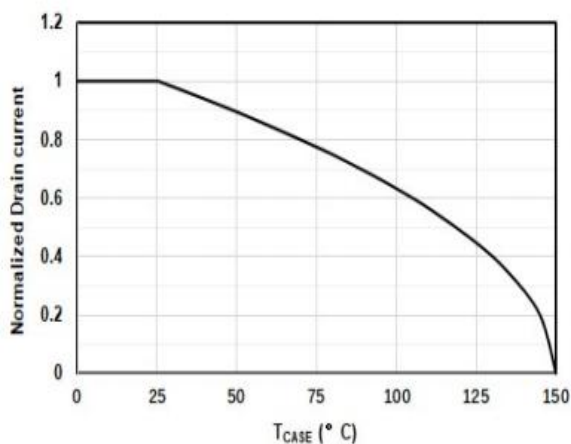


Figure 4: Drain Current vs.  $T_C$

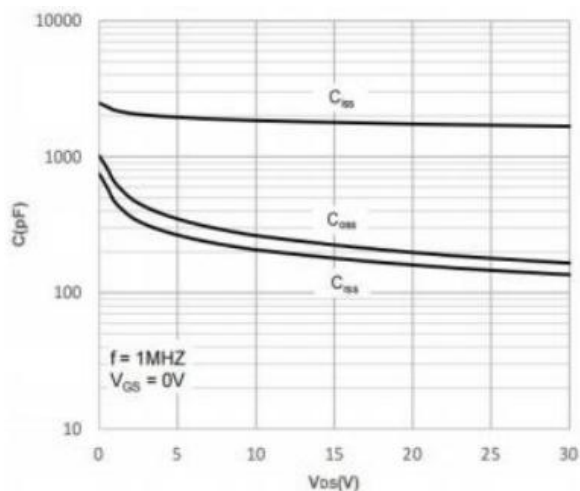


Figure 5: Capacitance Characteristics

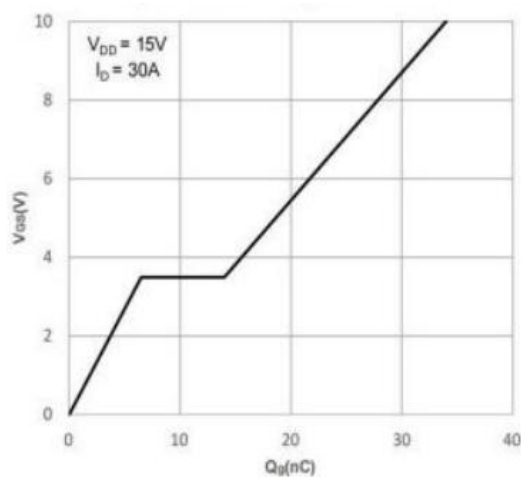


Figure 6: Gate-Charge Characteristics

■ Typical Characteristic Curve 典型特性曲线

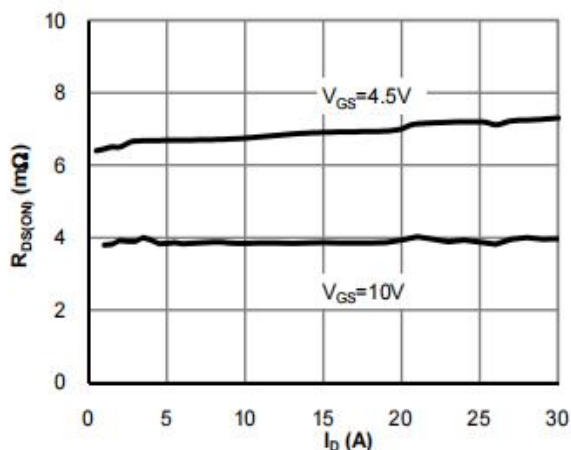


Figure 7: On-Resistance vs. Drain Current

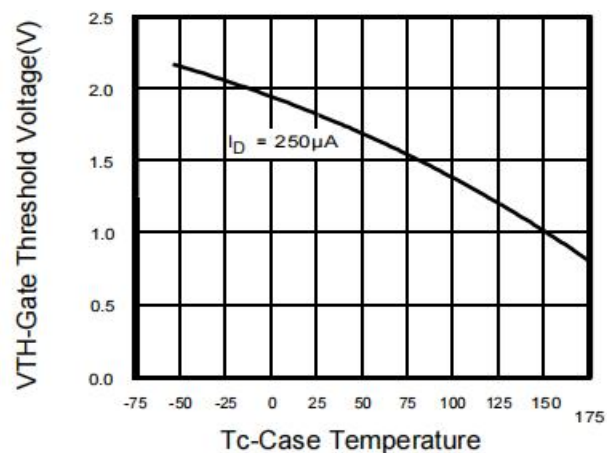


Figure 8: Threshold Voltage vs.  $T_C$

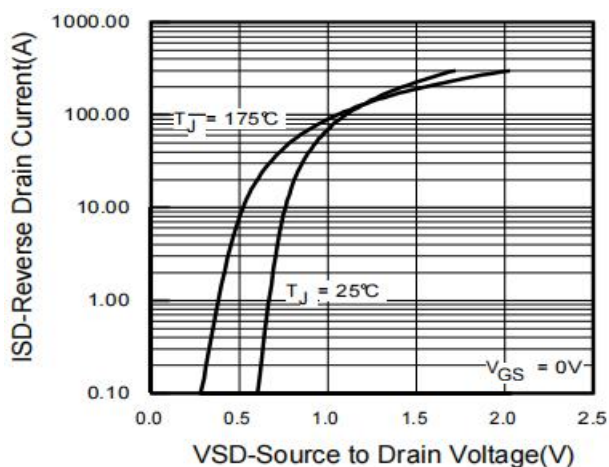


Figure 9: Diode Characteristics

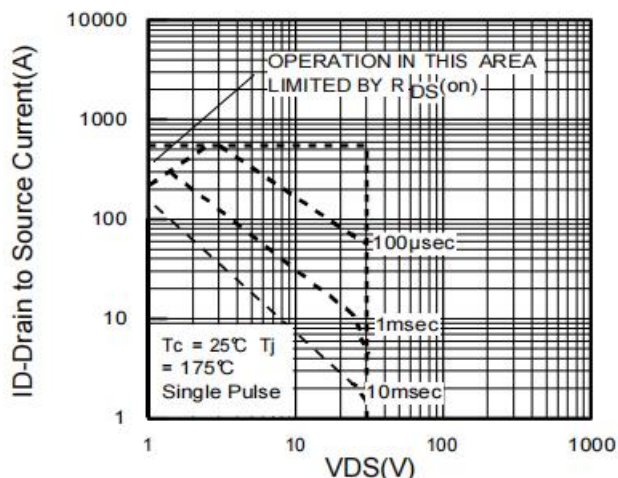


Figure 10: Safe Operating Area

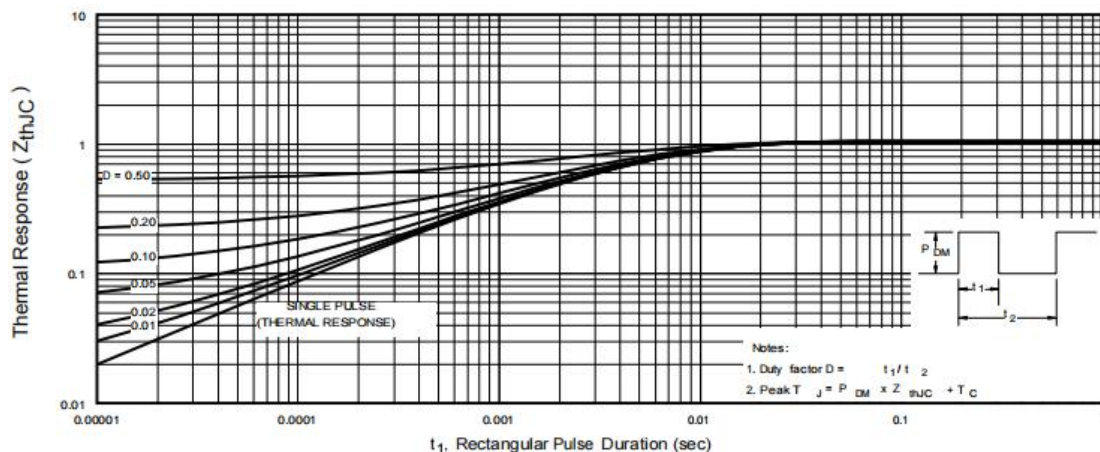
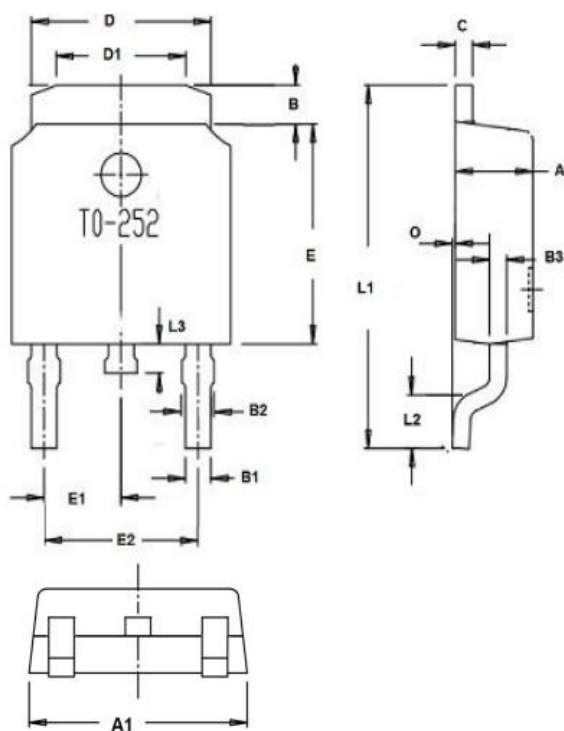


Figure 11: Transient Thermal Response Curve

## ■ Package Dimension 外形封裝尺寸



| Dim. | Min.   | Max. |
|------|--------|------|
| A    | 2.1    | 2.5  |
| A1   | 6.3    | 6.9  |
| B    | 0.95   | 1.55 |
| B1   | 0.6    | 0.8  |
| B2   | 0.75   | 0.95 |
| C    | Typ0.5 |      |
| D    | 5.3    | 5.5  |
| D1   | 3.65   | 4.05 |
| E    | 5.8    | 6.4  |
| E1   | Typ2.3 |      |
| E2   | Typ4.6 |      |
| O    | 0      | 0.15 |
| L1   | 9      | 11   |
| L2   | Typ1.5 |      |
| L3   | 0.7    | 1    |

All Dimensions in millimeter